



Call for Participation

2009 IEEE Asian Solid-State Circuits Conference (A-SSCC)

Nov. 16 - Nov. 18, 2009

The Grand Hotel, Taipei, Taiwan

Green Circuits for a Sustainable Society



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Contact/ Conference Secretary

Jun Tsai

Elite PCO

Tel: +886-2-8502-7087 Ext.28

E-mail: asscc2009@elitepco.com.tw

Sponsored by

IEEE Solid-State Circuits Society

Organized by

IEEE region 10 SCS chapters

Official Website

<http://www.a-sscc.org>

Important Dates:

Deadline of Early Registration:

Sept. 30, 2009 23:59 Taiwan(GMT+8)

Regular Registration:

Oct. 1, 2009 and onward

The IEEE SCS (Solid-State Circuits Society) fully supported Asian Solid-State Circuits Conference (A-SSCC) 2009 is an international forum for advances in solid-state circuits design held in Asia. Other than the conventional conference programs such as paper and plenary sessions, A-SSCC features a practical industry program. In the very fifth year under its name, the A-SSCC'09 received more than 280 papers. Technical program committee members are a balance of the industry and the academia and as a result, the technical program should interest both industry and academia.

Technical Paper Focus

"A DVS Embedded Power Management for High Efficiency Integrated SoC in UWB System"

"A 9b 100MS/S 1.46mW SAR ADC in 65nm CMOS"

"A Micro-Network on Chip with 10-Gb/s Transmission Link"

"Tera-Scale Performance Image Stream Processor with SoC Architecture for Multimedia Content Analysis"

"A 110GHz Inductor-Less CMOS Frequency Divider"

"A 1.35GHz All-Digital Fractional-N PLL with Adaptive Loop Gain Controller and Fractional Divider"

"A 1.3 pJ/B Inductive Coupling Transceiver with Adaptive Gain Control for Cm-Range 50Mbps Data Communication"

"A Low Supply Voltage Operation SRAM with HCI trimmed Sense Amplifiers"

"A 45nm 8-Core Enterprise Xeon® Processor"

Plenary Talks

• **Dr. Ho-Ming Tong** (Chief R&D Officer & GM, ASE Group, Taiwan)

"Green Future: IC Packaging Opportunities Abound"

• **Dr. Hisatsune Watanabe** (President, Semiconductor Leading Edge Technologies Inc., Japan)

"Nanoelectronics Devices: More CMOS, Fusion CMOS and Beyond CMOS"

• **Dr. Eric Vittoz** (Professor, Swiss Federal Institute of Technology, Lausanne, Switzerland)

"Weak Inversion for Ultra Low-Power and Very Low-Voltage Circuits"

Evening Panels

"Toward Low Voltage (0.5V) Design: Will Challenges Limit Operation?"

Moderator: Sreedhar Natarajan, (TSMC)

Panelists: K. Arimoto (Renesas), A. Burnet (Toumaz Medical), B. Nikolic (UCB), A. Keshavarzi(TSMC), P. Rickert (TI), and more

"Gigabit Transceiver: a Panacea or a Poison?"

Moderator: Mehmet Soyuer (IBM)

Panelists: M. Fujishma (Hiroshima Univ.), K. Nishikawa (NTT), B.Shung (SiBeam), L. Loh (MediaTek Inc.), A. Poon(Stanford Univ.), and more

Special Lecture

"All you need to know to write a winning ISSCC paper and give a smashing good presentation"

Dr. Jan Van Der Spiegel (Professor, University of Pennsylvania, USA)

Industrial Program

In the industry program, papers on cutting-edge IC products are presented with application, designed measurement information. There are two parallel sessions with 7 papers from Intel (USA), Toshiba (Japan), Sun Microsystems (USA), Rambus (USA), Innovision R&T (UK), Future Communication IC (Korea) and MediaTek Inc., (Taiwan).

Student Design Contest

10 outstanding chip designs from the accepted student papers will make real demonstrations on the conference site with authors' explanation. The best student design will be selected among those 10 demonstrations reflecting the high research standards of Asian academies.

Tutorials

"Silicon Microelectronic Chips in the Human Healthcare and Life Sciences" Donhee Ham (Harvard Univ.)

"Inductive-Coupling Through-Chip Interface for 3D System Integration" Tadahiro Kuroda (Keio Univ.)

"Emerging ADC design" Un-Ku Moon (Oregon State Univ.)

"Advanced RF and Analog Design in the Nano-Meter Era" Bram Nauta (Univ. of Twente)